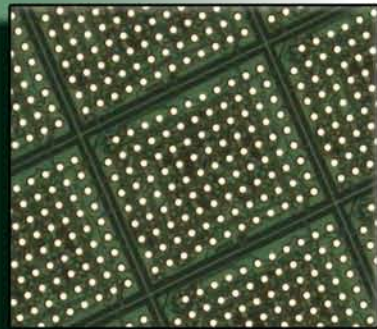


"The tangible benefit to Oracle is a 20:1 ROI on our membership investment. The intangibles are important too, chief of which is the informal atmosphere and frank discussion of mutual problems."

~ David Love, Oracle

Times Have Changed



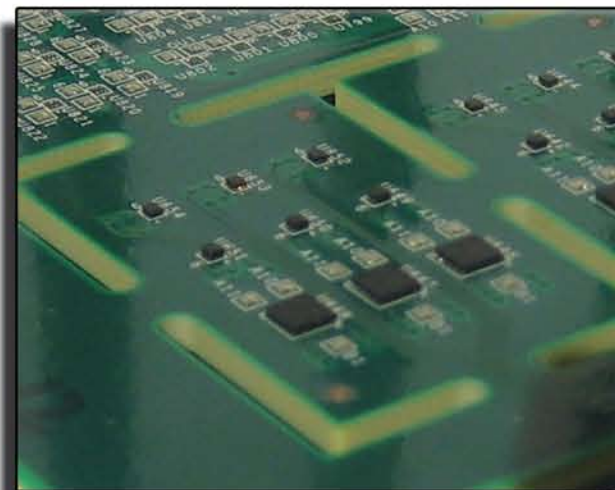
Change is part of life in the Electronics Industry, but the last decade has seen an unprecedented change in the industry's manufacturing structure, and as a result, in the way the industry conducts Research and Development (R&D). The System houses (OEMs) have divested themselves of

most of their manufacturing capabilities, and now depend on Electronics Manufacturing Companies (EMS providers) and ODMs located throughout the world to build their products. With the transfer of manufacturing, the OEMs have also passed on much of the responsibility for addressing future component and interconnect manufacturing challenges, giving up much of their own related technical expertise in the process.

The burden for PWB fabrication and assembly technology development has largely fallen on the EMS providers, who often lack the resources to undertake innovative developments outside the strict manufacturing area. Due to ever tightening margins, development effort needs to be focused and high payoff requiring close cooperation and direction from their customers, the OEMs. Opportunities for in-house speculative, "blue sky" R&D are extremely limited in today's industrial environment. This same situation is mirrored throughout the electronics supply chain, including the component and material suppliers. The industry is truly global, and the technology issues are global as well.

Common Challenges, Common Solutions

The pace of change of technology in the electronics industry continues relentlessly, putting increasing pressure on the need to find innovative and cost effective solutions to meet the expectations of today's society. An insatiable demand for greater processing power and increased bandwidth directly impacts integrated circuit design and associated interconnect technology. Add to this the impact of an increasingly environmentally enlightened market place forcing the need to adopt new materials and manufacturing processes and it is clear that industry R&D challenges are greater than ever. While product design innovation resides with the OEM, the responsibility for developing the manufacturing technology to fabricate new products falls on the complete supply chain, where common industry solutions represent the most cost effective answer to the challenges faced. Any introduction of new processes or materials requires extensive, time consuming and costly technical evaluation. By engaging players from multiple sectors of the supply chain in R&D activities, informed decisions and shared resources significantly increase the potential for successful and economical outcomes.



Are You Competitive?

Some of the most successful companies in our industry today have discovered the economies of scale and leveraging that pre-competitive cooperative R&D offers. By joining together with their EMS providers, their EMS providers' suppliers, and yes, even their competitors; sharing scarce resources and expertise to address issues of common interest; they have resolved major industry problems in a fraction of the time and at a fraction of the cost it would take to do it alone.

At HDP User Group our members recognize the power of inter-company cooperation and leverage the opportunities that the organization offers to collaboratively tackle technical problems on many fronts.

Why Be a Part of HDP User Group?

- * Develop and validate new technologies at a fraction of the investment required to achieve in-house.
- * Learn and benefit from working with experts across the complete electronics industry supply chain.
- * Enjoy an open minded and dynamic environment focused on pre-competitive research and testing activities free from intellectual property constraints and complications.
- * Lead, influence, provide resources, advise or merely monitor projects. You decide the amount of involvement and commitment to any of the projects undertaken.
- * Leverage results and test data generated and overseen by industry experts.
- * Network with leading companies within the electronics field. Raise your own company's profile and gain a more informed understanding of the challenges faced by the industry as a whole.

Benefits of Membership

HDP User Group brings together like minded technical experts from across the electronics industry to address many of today's component packaging and interconnect challenges. Members enjoy the benefit of:

- * An international organization with participation from members located in Europe, Asia and North America.
- * An extensive list of members representing the world's leading system integrators, PWB fabricators / assemblers, and component and material suppliers.
- * A broad range of collaborative projects developed in direct response to member's needs.
- * An open environment where experts can exchange ideas and identify solutions to common technical issues.
- * A highly experienced and dedicated facilitation team to support rapid and efficient project execution.
- * A comprehensive website allowing members only (password protected) access to results from all projects (past and present) as soon as they become available.
- * Quarterly face to face members meetings throughout the world, complemented by regular project meetings hosted over internet conferencing facilities.

Become a Member

HDP User Group membership is available to companies who are involved in using, designing or manufacturing electronic component packaging and interconnect solutions including:

- * System Integrators
- * Component Suppliers
- * PWB Fabricators
- * Assembly Houses and EMS Providers
- * Materials & Equipment Suppliers

For membership details and an application, visit www.hdpug.org